



# FDP5800

## N-Channel Logic Level PowerTrench® MOSFET

60V, 80A, 6mΩ

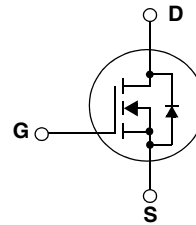
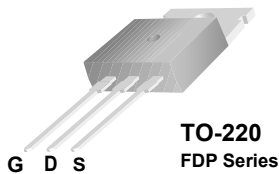
### Features

- $R_{DS(on)} = 4.6m\Omega$  (Typ.),  $V_{GS} = 10V$ ,  $I_D = 80A$
- High performance trench technology for extremely low  $R_{Dson}$
- Low gate Charge
- High power and current handling capability
- RoHs Compliant



### Applications

- Motor/ Body Load Control
- Power Train Management
- Injection Systems
- DC-AC Converters and UPS



### MOSFET Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted\*

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current	-Continuous ( $T_C = 25^\circ C$ )	80
		-Continuous ( $T_C = 100^\circ C$ )	80*
		-Continuous ( $T_A = 25^\circ C$ )	14
$I_{DM}$	Drain Current - Pulsed	320	A
$E_{AS}$	Single Pulsed Avalanche Energy (Note 1)	652	mJ
$P_D$	Power Dissipation ( $T_C = 25^\circ C$ ) - Derate above $25^\circ C$	242	W
		1.61	W/ $^\circ C$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	$^\circ C$

\*Drain current limited by package

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.62	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, 1in <sup>2</sup> copper pad area	43	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	$^\circ C/W$

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP5800	FDP5800	TO220	--	--	50

**Electrical Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
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**Off Characteristics**

$B_{VDSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$ , $T_J = 25^\circ\text{C}$	60	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 48\text{V}$ $V_{GS} = 0\text{V}$ $T_J = 150^\circ\text{C}$	--	--	1	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current, Forward	$V_{GS} = \pm 20\text{V}$ , $V_{DS} = 0\text{V}$	--	--	$\pm 100$	nA

**On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$	1.0	--	2.5	V
$R_{DS(on)}$	Static Drain-Source On Resistance	$V_{GS} = 10\text{V}$ , $I_D = 80\text{A}$	--	4.6	6.0	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}$ , $I_D = 80\text{A}$	--	5.9	7.2	$\text{m}\Omega$
		$V_{GS} = 5\text{V}$ , $I_D = 80\text{A}$	--	5.6	7.0	$\text{m}\Omega$
		$V_{GS} = 10\text{V}$ , $I_D = 80\text{A}$ $T_J = 175^\circ\text{C}$	--	10.4	12.6	$\text{m}\Omega$

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 15\text{V}$ , $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	--	6890	9160	pF
$C_{oss}$	Output Capacitance		--	750	1000	pF
$C_{rss}$	Reverse Transfer Capacitance		--	295	445	pF
$R_G$	Gate Resistance	$V_{GS} = 0.5\text{V}$ , $f = 1\text{MHz}$	--	1.2	--	$\Omega$
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0\text{V}$ to 10V	--	112	145	nC
$Q_{g(TH)}$	Total Gate Charge at 5V	$V_{GS} = 0\text{V}$ to 5V	--	58	--	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0\text{V}$ to 1V	--	7.0	--	nC
$Q_{gs}$	Gate to Source Gate Charge	$V_{DS} = 30\text{V}$ $I_D = 80\text{A}$ $I_g = 1\text{mA}$	--	23	--	nC
$Q_{gs2}$	Gate Charge Threshold to Plateau		--	13	--	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		--	18	--	nC

**Switching Characteristics ( $V_{GS} = 10\text{V}$ )**

$t_{ON}$	Turn-On Time	$V_{DD} = 30\text{V}$ , $I_D = 80\text{A}$ $V_{GS} = 10\text{V}$ , $R_{GEN} = 1.5\Omega$	--	37	85	ns
$t_{d(on)}$	Turn-On Delay Time		--	18	46	ns
$t_r$	Turn-On Rise Time		--	19	47	ns
$t_{d(off)}$	Turn-Off Delay Time		--	55	120	ns
$t_f$	Turn-Off Fall Time		--	9	28	ns
$t_{OFF}$	Turn-Off Time		--	64	138	ns

**Drain-Source Diode Characteristics**

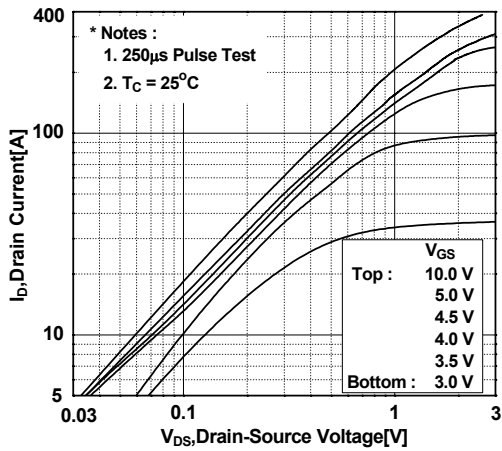
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{V}$ , $I_{SD} = 80\text{A}$	--	--	1.25	V
		$V_{GS} = 0\text{V}$ , $I_{SD} = 40\text{A}$	--	--	1.0	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{V}$ , $I_{SD} = 60\text{A}$	--	58	--	ns
$Q_{rr}$	Reverse Recovery Charge	$di_f/dt = 100\text{A}/\mu\text{s}$	--	106	--	nC

**Notes:**

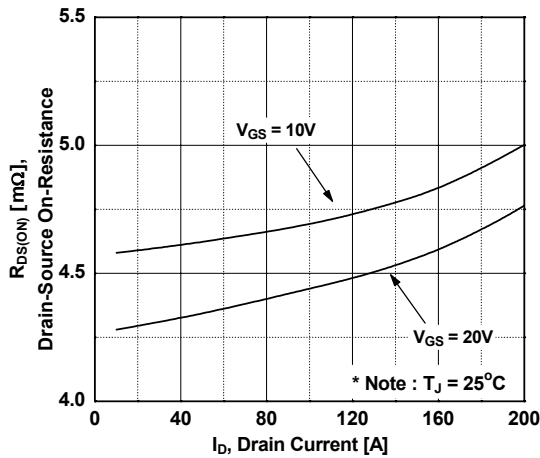
1:  $L = 1\text{mH}$ ,  $I_{AS} = 36\text{A}$ ,  $V_{DD} = 54\text{V}$ ,  $V_{GS} = 10\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

## Typical Performance Characteristics

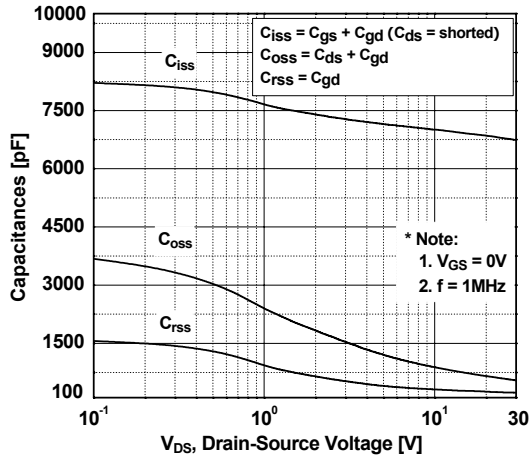
**Figure 1. On-Region Characteristics**



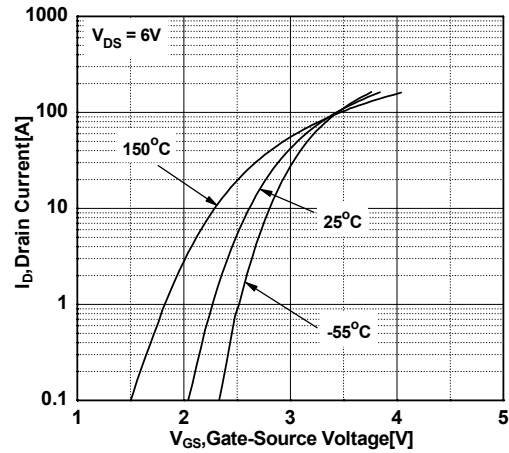
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



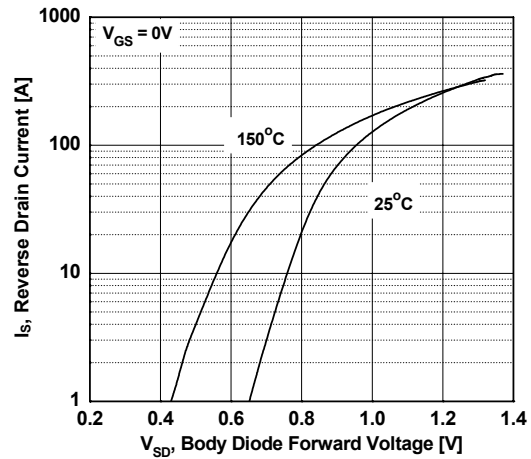
**Figure 5. Capacitance Characteristics**



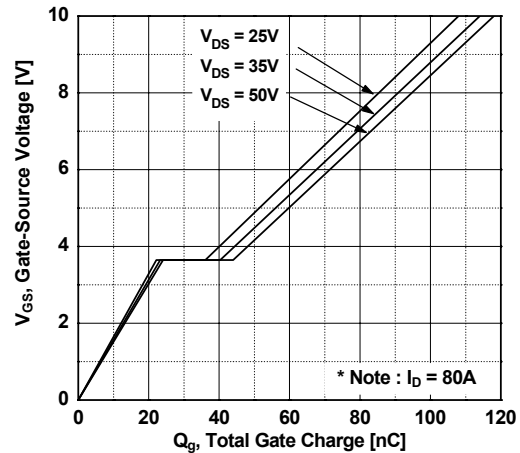
**Figure 2. Transfer Characteristics**



**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 6. Gate Charge Characteristics**



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

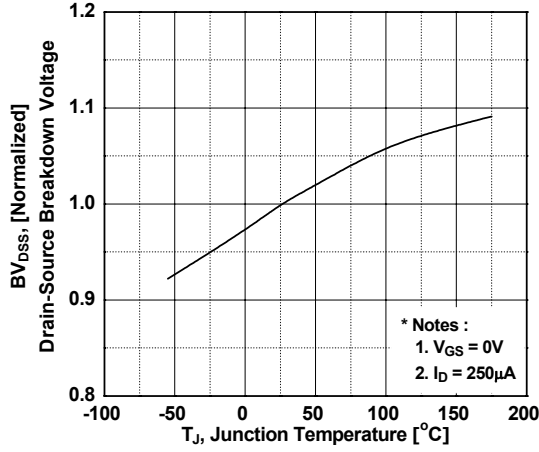


Figure 8. On-Resistance Variation vs. Temperature

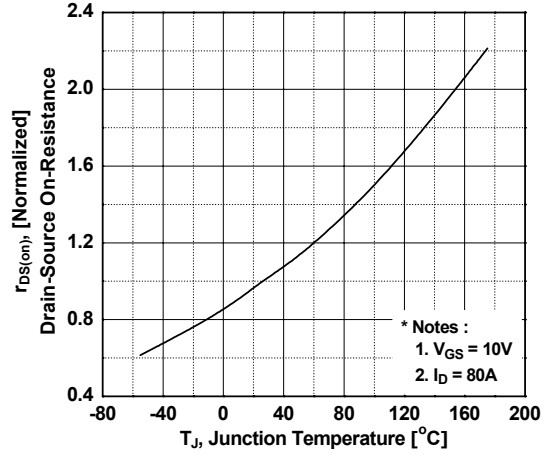


Figure 9. Maximum Safe Operating Area

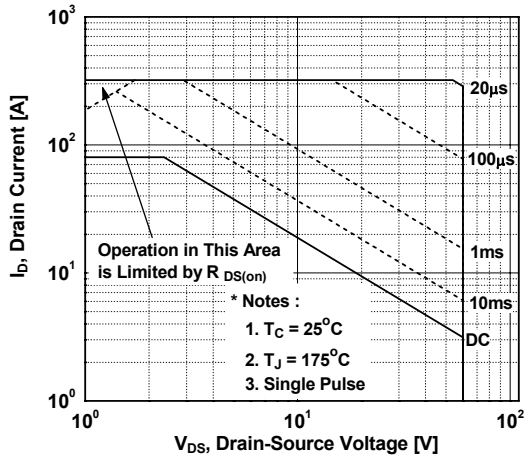


Figure 10. Maximum Drain Current vs. Case Temperature

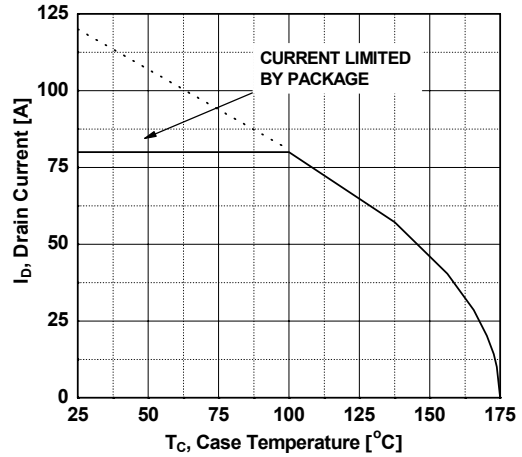
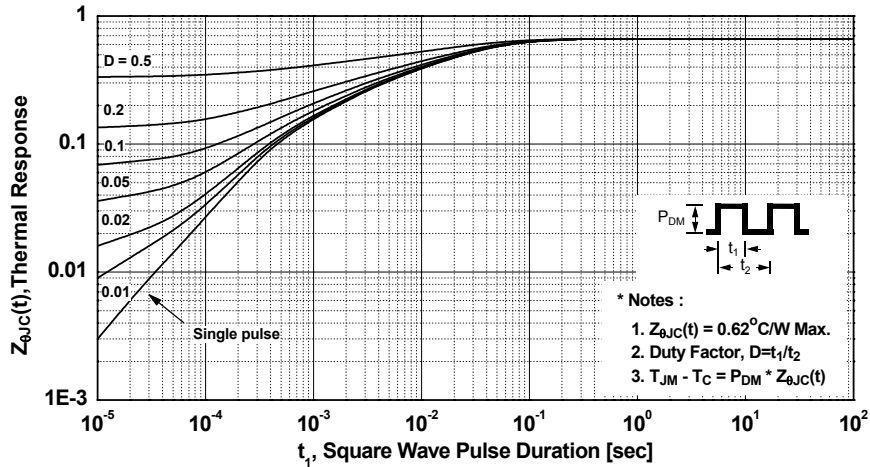
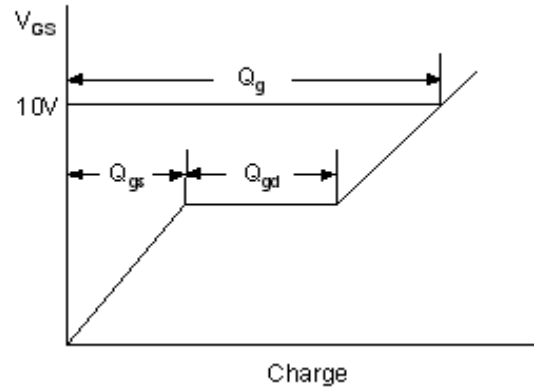
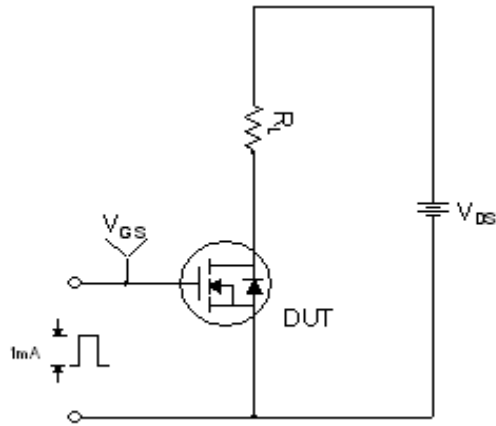


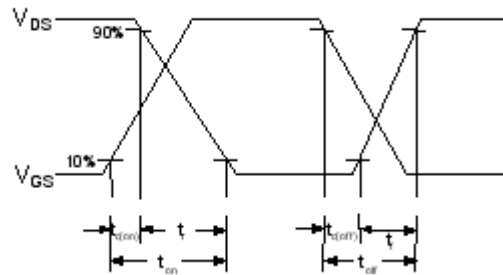
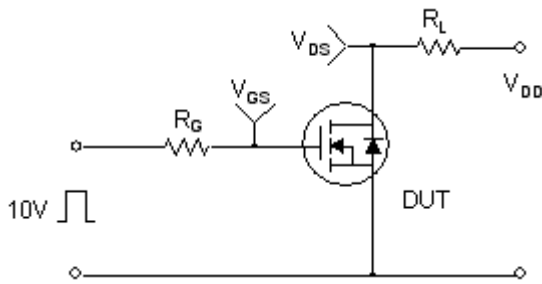
Figure 11. Transient Thermal Response Curve



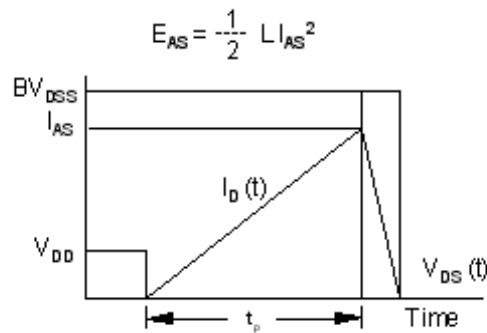
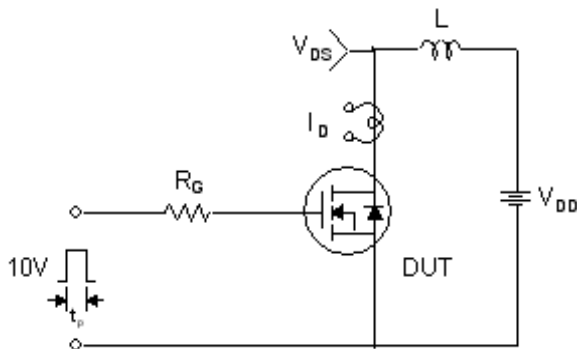
**Gate Charge Test Circuit & Waveform**



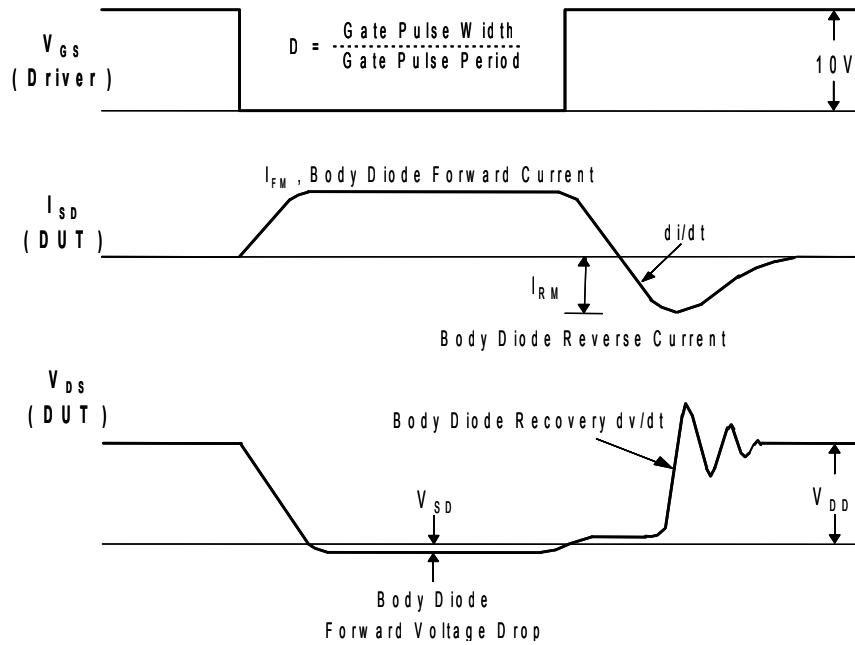
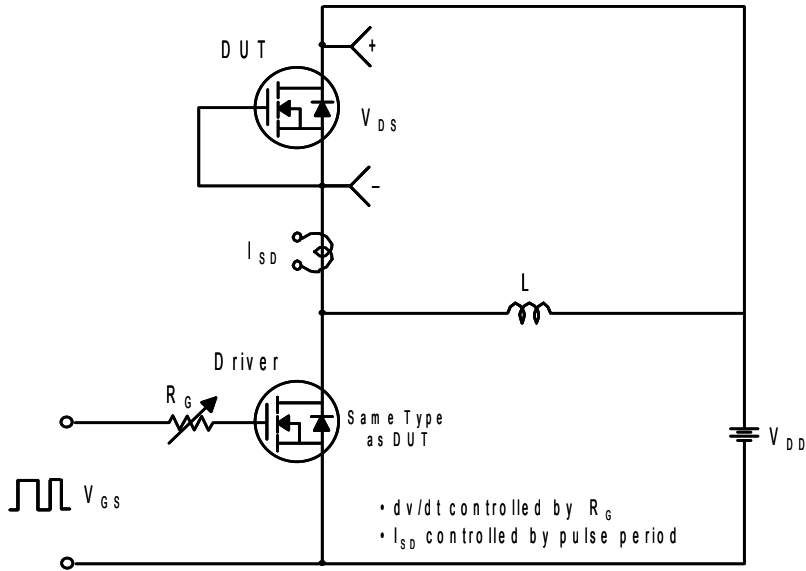
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**



Peak Diode Recovery dv/dt Test Circuit & Waveforms





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